



A+ Product Portfolio

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Supermicro Performance Leadership



Achieve world record performances across major industry benchmarks with Supermicro A+ platforms

Over 35 World Records in Performance

FP & Integer



SPECrate 2017 Floating Point

A+ BigTwin

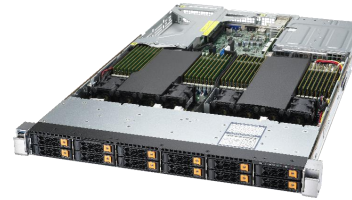
- Best 2-node 4 CPU
- Best 4-node 8 CPU
- Best 8-node 16 CPU
- Best 16-node 32 CPU
- Best Overall

SPECrate 2017 Integer

A+ BigTwin

- Best 2-node 4 CPU
- Best 4-node 8 CPU
- Best 8-node 16 CPU
- Best 16-node 32 CPU
- Best Overall

Java



SPECjbb 2015-Composite

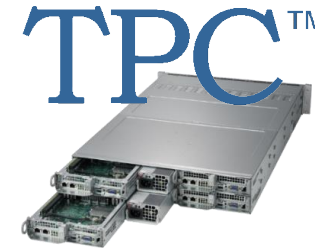
A+ Ultra

- Best 1-node 2 CPU
- Best Overall

SPECjbb 2015-Distributed

A+ BigTwin

- Best 4-node



TPC-C Benchmark (Transactions)

A+ Ultra

- Best 1-node 2 CPU price/performance
- Best 1-node 2CPU

TPC-DS Benchmark (BigData)

A+ BigTwin

- Best 1-node overall price/performance
- Best 16-node 2CPU

TPCx-IoT Benchmark (IoT)

A+ TwinPro

- Best 4-node 1 CPU
- Best overall
- Best over CPU price/performance



A+ WIO (Storage)

Record performance of 217 GB/s was measured on just 6-nodes of *Supermicro WIO platform* w/Milan 74F3 CPU, 2x200 Gb/s CX6 IO, and 20 Kioxia PCIe4 NVME drives (per node). 36GB/s of read throughput per node.

A+ Servers, Rome & Milan



Rackmount Servers

GPU Optimized Servers

A+ H12 Platforms

2nd Gen
AMD EPYC
“Rome”

3rd Gen
AMD EPYC
“Milan”

BIOS 2.0 & later
8 Memory Channels
NVMe/PCIe 4.0
128 PCIe Lanes
DDR4-3200, up to 8TB
Max 280W TDP

Multi-node Servers

Towers





Latest Generation A+ Systems

Broadest Portfolio Optimized to Deliver Superior Performance with AMD EPYC™ Family of Processors



H12 2U2N GPU



Redstone
2124GQ-NART



Delta
424G0-NART

4U 8 GPU
4124GS-TNR



H12 TwinPro 4-Node
3.5" Drive Bays



H12 BigTwin 4-Node
2.5" Drive Bays



H12 FatTwin™



Blade



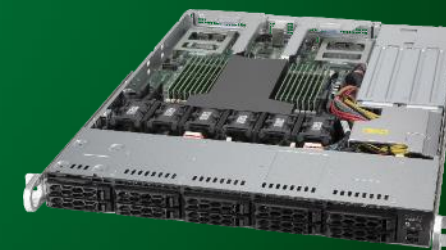
H12 Ultra



H12 W10 NVMe



H12 W10
2.5" / 3.5" Drive Bays



H12 CloudDC

Rackmount Servers

1U & 2U Stand-alone Versatile Servers

1U & 2U Standard 19" Rackmount

Ultra:

- 1024US-TRT
- 2024US-TRT
- 1124US-TNRP
- 2124US-TNRP

WIO:

- 1014S-WTRT
- 1114S-WTRT
- 1114S-WN10RT
- 2114S-WN24RT



Cloud DC:

- 1114CS-TNR
- 2014CS-TR

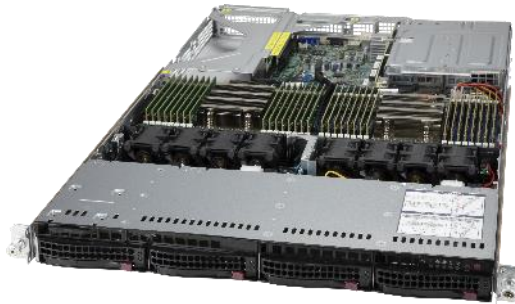
Mainstream:

- 2014S-TR

Ultra 1U/2U: AS -1024US-TRT/2024US-TRT



DP Ultra 32DIMM 1U/2U, Flexible networking with Ultra Riser



- **Key Features**
 - Dual AMD EPYC™ 7002/7003 Series Processors
 - 32 DIMMs up to 8TB DDR4 3200MHz
 - 2U 12 SATA & 1U 4 SATA, optional U.2 NVMe support
 - PCIe Gen 4.0
- **Key Applications**
 - Virtualization
 - Cloud Computing
 - High End Enterprise Server
 - Hyperconverged Storage



Specifications

CPU – Dual Socket Dual AMD EPYC™ 7002/7003 Series Processors Up to 128 Cores, CPU TDP up to 280W	Memory – 32 DIMM Slots 32 DIMMs, up to 8TB Registered ECC DDR4 3200MHz SDRAM
Drives – 4 and 12 Hot-Swap Bays 1U: 4x 3.5" SATA/NVMe Hybrid 2U: 12x 3.5" SATA/NVMe Hybrid	Expansion – 4 and 6 PCI-E Slots 1U: 3x PCI-E x16 & 1x PCI-E x16 Internal 2U: 4x PCI-E x16 & 2 PCI-E x8 LP (1 Internal x8)
Networking – Dual 10GbE 2x RJ45 10GbE 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 1U: 2x 1000W Titanium Level 2U: 2x 1600W Titanium Level

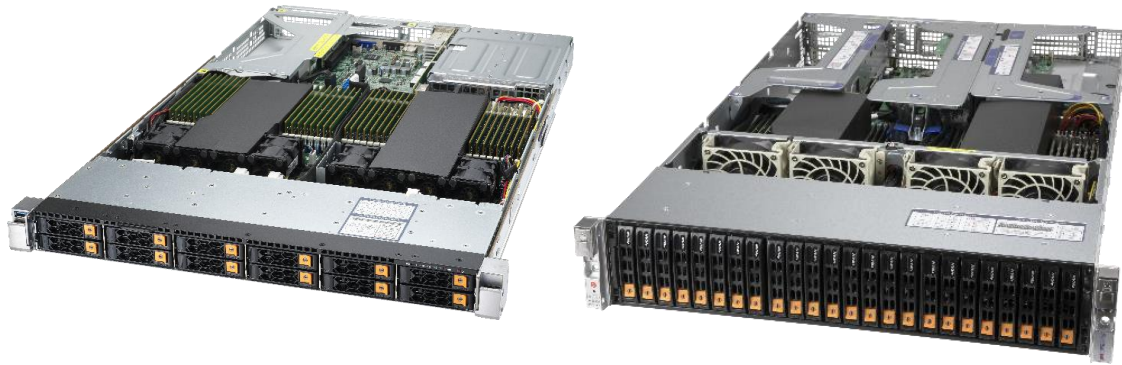
*(Full redundancy based on configuration and application load)

Subject to change without notice

Ultra 1U/2U: AS -1124US-TNRP/2124US-TNRP



DP Ultra 32DIMM 1U/2U, All direct attached NVMe



- **Key Features**
 - Dual AMD EPYC™ 7002/7003 Series Processors
 - 32 DIMMs up to 8TB DDR4 3200MHz
 - 1U 2.5" 12 NVMe and 2U 2.5" 24 NVMe optional SATA
 - PCIe Gen 4.0
- **Key Applications**
 - Virtualization
 - Cloud Computing
 - Hyperconverged Storage
 - High-End Enterprise Server

Specifications

CPU – Dual Socket Dual AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 32 DIMM Slots 32 DIMMs, up to 8TB Registered ECC DDR4 3200MHz SDRAM
Drives – 12 and 24 2.5" Bays 1124US: 12x 2.5" NVMe 2124US: 24x 2.5" NVMe	Expansion 1124US: 3 PCIe Gen 4x 16, 1 Internal Gen 4 x16 2124US: 1 PCIe Gen 4 x16
Networking – Dual 10GbE 2x RJ45 10GbE + 2 SFP+ ports 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 1124US: 1200W Titanium Level 2124US: 1600W Titanium Level



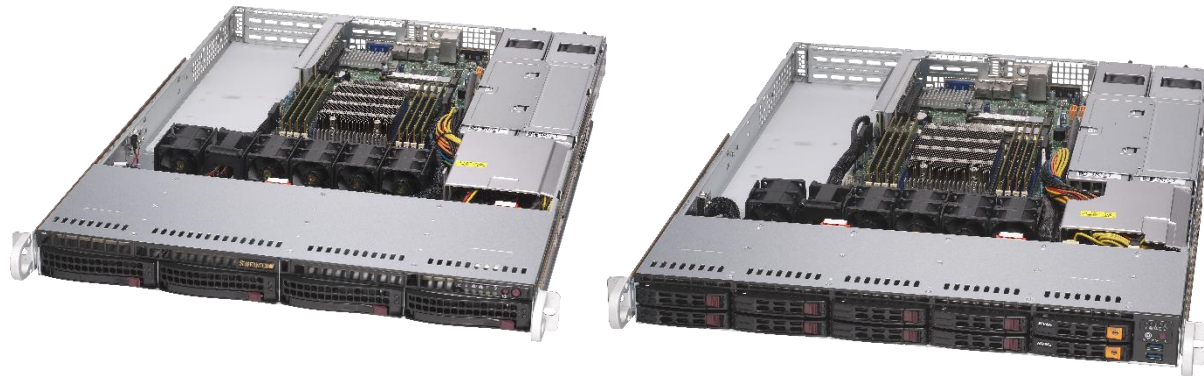
Subject to change without notice

*(Full redundancy based on configuration and application load)

*(Full redundancy based on configuration and application load)

WIO 1U: AS -1014S-WTRT/1114S-WTRT

UP WIO 8DIMM 1U, Support Nvidia T4



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 3.5" 4 SATA or 4 NVMe, 2.5" 10 SATA or 8 SATA + 2 NVMe
 - PCIe Gen 4.0
- **Key Applications**
 - DB Processing & Processing
 - Data Center Applications
 - Firewall Application



Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 4 and 10 Hot-Swap Bays 1014S: 4x 3.5" SATA/NVMe Hybrid 1114S: 10x 2.5" SATA/NVMe Hybrid (up to 2x NVMe)	Expansion – 3 PCI-E Slots 2x PCI-E Gen 4 x16 FHFL 1x PCI-E Gen 4 x16 LP
Networking – Dual 10GbE 2x RJ45 10GbE 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 500W Platinum Level

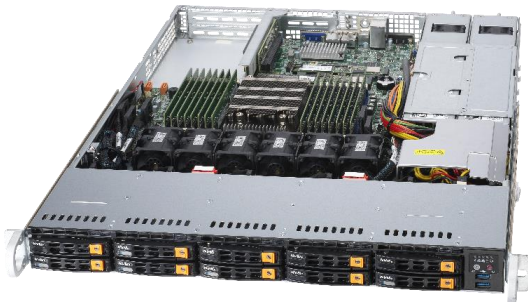
*(Full redundancy based on configuration and application load)

Subject to change without notice

WIO 1U/2U: AS -1114S-WN10RT/2114S-WN24RT



UP WIO 16DIMM 1U/2U, All direct attached NVMe



• Key Features

- Single AMD EPYC™ 7002/7003 Series Processors
- 16 DIMMs up to 4TB DDR4 3200MHz
- 1U 2.5" 10 NVMe and 2U 2.5" 24 NVMe optional SATA
- PCIe Gen 4.0

• Key Applications

- Virtualization
- Cloud Computing
- Hyperconverged Storage
- All Flash Storage



Specifications

CPU – Single Socket

Single AMD EPYC™ 7002/7003 Series Processors
Up to 64 Cores, CPU TDP up to 280W

Memory – 32 DIMM Slots

16 DIMMs, up to 4TB Registered ECC DDR4
3200MHz SDRAM

Drives – 10 and 24 2.5" Bays

1114S: 10x 2.5" NVMe
2114S: 24x 2.5" NVMe

Expansion

1114S: 3 PCIe Gen 4x 16 (2x FHFL, 1x LP)
2114S: 1 PCIe Gen 4 x16

Networking – Dual 10GbE

2x RJ45 10GbE
1x RJ45 1GbE IPMI

Power Supply – 1+1 Redundant

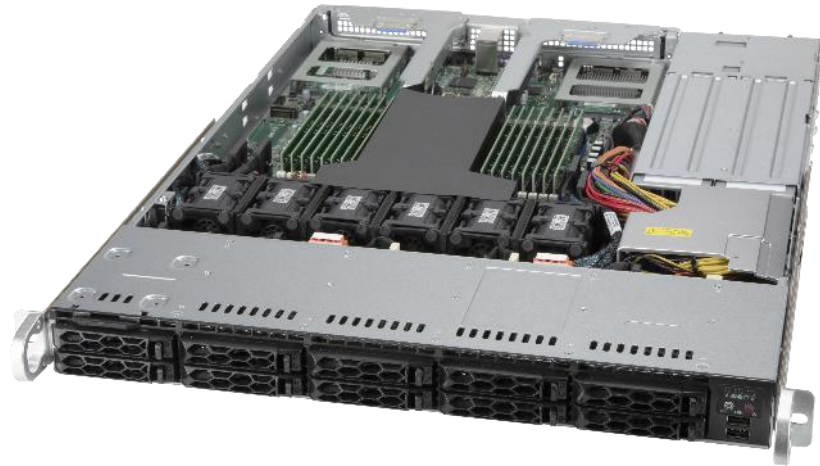
1114S: 750W Platinum Level
2124S: 1200W Titanium Level

Subject to change without notice

*(Full redundancy based on configuration and application load)

Cloud DC 1U: AS -1114CS-TNR

UP Cloud DC 16DIMM 1U, Flexible networking with AIOM

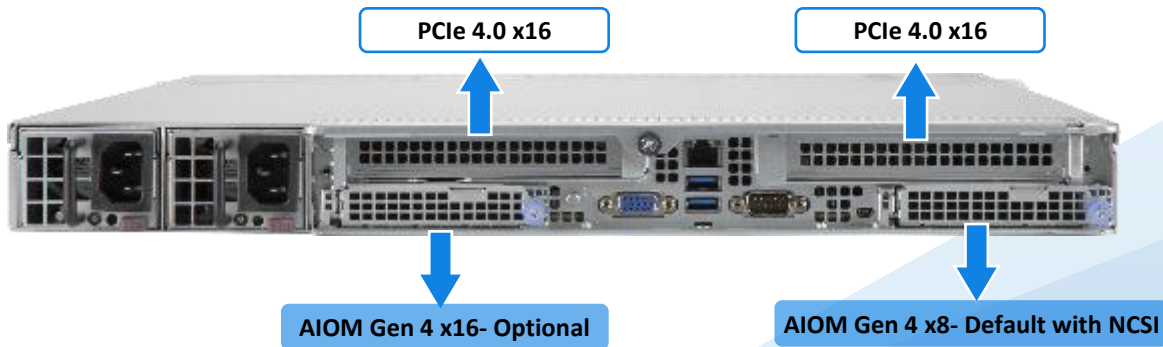


- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 16 DIMMs up to 4TB DDR4 3200MHz
 - 2.5" 10 SATA / NVMe
 - AIOM
 - PCIe Gen 4.0
- **Key Applications**
 - Cloud Computing
 - CDN
 - Deep Learning Inferencing

Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 16 DIMM Slots 16 DIMMs, up to 4TB Registered ECC DDR4 3200MHz SDRAM
Drives – 10 Drive Bays 10x SATA (optional SAS/NVMe with additional kits) 2x NVMe M.2	Expansion – 2 PCI-E Slots 2x PCI-E Gen 4.0 x16 FHHL
Networking 2x AIOM (1 x16 and 1 x8 with NCSI) 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 860W Platinum Level

*(Full redundancy based on configuration and application load)



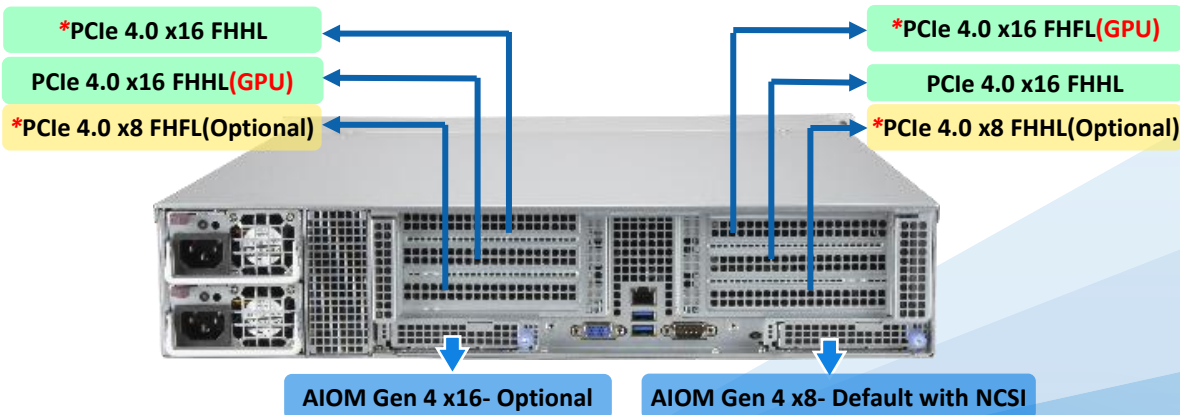
Subject to change without notice

Cloud DC 2U: AS -2014CS-TR

UP Cloud DC 16DIMM 2U, Flexible networking with AIOM, GPU support



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 16 DIMMs up to 4TB DDR4 3200MHz
 - 3.5" 12x SATA (optional 4x NVMe/ 12 xSAS with additional kits)
 - 2 x DW or 6 x T4 GPU
 - PCIe Gen 4.0 AOC/AIOM
- **Key Applications**
 - Cloud Computing
 - CDN
 - Deep Learning Inferencing



• Configurable with 1 x16 or 2 x8
Subject to change without notice

Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 16 DIMM Slots 16 DIMMs, up to 4TB Registered ECC DDR4 3200MHz SDRAM
Drives – 12 Drive Bays 12x SATA (optional 4x NVMe/ 12 xSAS with additional kits)	Expansion – 4 PCI-E Slots 2x PCI-E 4.0 x16 2x PCI-E 4.0 x16 (Can convert to 4x PCI-E4.0 x8)
Networking 2x AIOM (1 x16 and 1 x8 with NCSI) 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 920W Platinum Level

Mainstream 2U: AS -2014S-TR

UP Mainstream 8DIMM 2U, Based on ATX board



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 12 hot-swap 3.5" SATA/SAS in front + 2 2.5" in the rear
 - PCIe Gen 4.0
- **Key Applications**
 - Backup storage
 - Web or Database Servers
 - Compact Network Appliance

Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 12 3.5" + 2 2.5" Drive Bays 12 3.5" hot swap SATA/SAS in front 2 2.5" SATA in rear	Expansion – 3 PCI-E Slots 5x PCI-E Gen 4 x16 2x PCI-E Gen 4 x8
Networking – Dual 1GbE 2x RJ45 1GbE	Power Supply – 1+1 Redundant 2x 920W Platinum Level

*(Full redundancy based on configuration and application load)

Subject to change without notice

Multi-Node Servers

2U/4U/8U Multi-Node Robust Servers

Resource Saving Architecture

SuperBlades:

- 4114S-C2N
- 4114S-T2N
- 4119GS



FatTwin:

- F1114S-FT
- F1114S-RNTR
- F2014-RNTR



BigTwin:

- 2024BT-HTR
- 2124BT-HNTR

TwinPro:

- 2014TP-HTR

BigTwin 2U Server: AS -2124BT-HTR/HNTR



DP 2U 4node, Flexible Network via SIOM



- **Key Features**
 - Dual AMD EPYC™ 7002/7003 Series Processors
 - 16 DIMMs up to 4TB DDR4 3200MHz
 - 2U 4-node, resource saving architecture
 - PCIe Gen 4.0
- **Key Applications**
 - Compute Intensive Applications
 - HPC, Data Center, Enterprise Applications
 - Hyperscale / Hyperconverged



Specifications

CPU – Dual Socket per node Dual AMD EPYC™ 7002/7003 Series Processors Up to 128 Cores, CPU TDP up to 240W* (HNTR)	Memory – 16 DIMM Slots per node 16 DIMMs, up to 4TB Registered ECC DDR4 3200MHz SDRAM
Drives – 6 Hot-Swap Bays per node HTR: 6x 2.5" SATA HNTR: 6x 2.5" SATA/NVMe Hybrid (up to 4x NVMe)	Expansion – 2 PCI-E Slots per node 2x PCI-E x16 LP
Networking – Flexible via SIOM per node 1x SIOM 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 2200W Titanium Level**

*Certain CPUs with high TDP may be supported only under specific conditions.

**Full redundancy based on configuration and application load

Subject to change without notice

TwinPro 2U Server: AS -2014TP-HTR

UP 2U 4-node, Flexible Network via SIOM



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 2U 4-node, resource saving architecture
 - PCIe Gen 4.0
- **Key Applications**
 - Compute Intensive Applications
 - HPC, Data Center, Enterprise Applications
 - Hyperscale / Hyperconverged

Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W*	Memory – 8 DIMM Slots per node 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 3 Hot-Swap Bays per node 6x 3.5" SATA	Expansion – 2 PCI-E Slots per node 2x PCI-E x16 LP
Networking – Flexible via SIOM per node 1x SIOM 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 2000W Titanium Level**

*Certain CPUs with high TDP may be supported only under specific conditions.

**Full redundancy based on configuration and application load

Subject to change without notice

SuperBlade 8U Server: SBA-4114S-C2N/T2N



UP 8U 20-node, density optimized server



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 8U 20-node, resource saving architecture, Front serviceability
 - PCIe Gen 4.0
- **Key Applications**
 - Compute Intensive Applications
 - HPC, Data Center, Enterprise Applications



Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots per node 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 2 Bays per node T2N: 2x 2.5" NVMe/SATA, 2x M.2 connector C2N: 2x 2.5" NVMe/SATA/SAS (SAS AOM), 2x M.2	Expansion – 1 PCI-E Slots per node 1x PCI-E x16 or 2x PCI-E x8 AIOM
Networking – Flexible via Mezzanine per node Mezzanine (25G/EDR/HDR) 2x onboard 25G, 1x Built-in video from BMC	Power Supply – 8 Redundant power supply 8x 2200W Titanium Level**

Subject to change without notice

SuperBlade 8U Server: SBA-4119GS



UP 8U 20-node, density optimized server with GPU support



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 8U 20-node, resource saving architecture, Front serviceability
 - 1 double width GPU or 2 single width GPU support
 - PCIe Gen 4.0
- **Key Applications**
 - Compute Intensive Applications
 - HPC, Data Center, Enterprise Applications



Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots per node 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 1 M.2 per node 1x M.2	Expansion – 2 PCI-E Slots per node 2x PCI-E x16
Networking – Flexible via Mezzanine per node Mezzanine (25G/EDR/HDR) 2x onboard 25G, 1x Built-in video from BMC	Power Supply – 8 Redundant power supply 8x 2200W Titanium Level**

Subject to change without notice

FatTwin 4U Front I/O Server: AS –F1114S-FT



UP 4U 8-node, density optimized Front I/O, Front serviceability



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 16 DIMMs up to 4TB DDR4 3200MHz
 - 4U 8-node, resource saving architecture, Front serviceability
 - PCIe Gen 4.0
- **Key Applications**
 - Hyperscale and Hyperconverged Solutions
 - Cloud Computing
 - HPC



Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 16 DIMM Slots per node 16 DIMMs, up to 4TB Registered ECC DDR4 3200MHz SDRAM
Drives – 3.5” or 2.5” Drives per node 2x 3.5” or 4x 2.5” internal drive bays 2x M.2 (NVMe or SATA) up to 110mm	Expansion – 2 PCI-E Slots per node 2x PCI-E x16 LP Riser
Networking – Flexible via AIOM per node 1x AIOM 1x RJ45 1GbE IPMI	Power Supply – 4 Redundant power supply 4x 2200W Titanium Level

Subject to change without notice

FatTwin 4U Rear I/O Server: AS –F114S-RNTR



UP 4U 8-node, density optimized Rear I/O, Front serviceability



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 4U 8-node, resource saving architecture, Front serviceability
 - PCIe Gen 4.0
- **Key Applications**
 - Hyperscale and Hyperconverged Solutions
 - Virtualization
 - HPC and Big Data
 - Data Center Enterprise Application



Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots per node 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 6 Drive Bays per node 6x 2.5" NVMe/SATA 4x M.2 (NVMe/SATA) up to 110mm	Expansion – 1 PCI-E Slots per node 1x PCI-E x16 LP Riser
Networking – Flexible via AIOM per node 1x AIOM 1x RJ45 1GbE IPMI	Power Supply – 4 Redundant power supply 4x 2200W Titanium Level

Subject to change without notice

FatTwin 4U Rear I/O: AS –F2014S-RNTR



UP 4U 4-node, density optimized Rear I/O, Front serviceability



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 4U 4-node, resource saving architecture, Front serviceability
 - PCIe Gen 4.0
- **Key Applications**
 - Hyperscale and Hyperconverged Solutions
 - Virtualization
 - HPC and Big Data
 - Data Center Enterprise Application



Specifications

CPU – Single Socket per node Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots per node 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 8 Drive Bays per node Front 6x 3.5” SATA (Optional NVMe Support) Rear 2x 3.5” SATA/NVMe 4x M.2 (NVMe/SATA) up to 110mm	Expansion – 1 PCI-E Slots per node 1x PCI-E x16 LP Riser 1x PCI-E x8 for Internal RAID AOC
Networking – Flexible via AIOM per node 1x AIOM 1x RJ45 1GbE IPMI	Power Supply – 4 Redundant power supply 4x 2200W Titanium Level

Subject to change without notice

GPU Optimized Servers



2U & 4U GPU Servers

AI/ML GPU Architectures

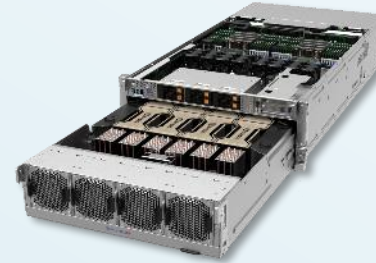
4U 160 PCIe:

- 4124GS-TNR



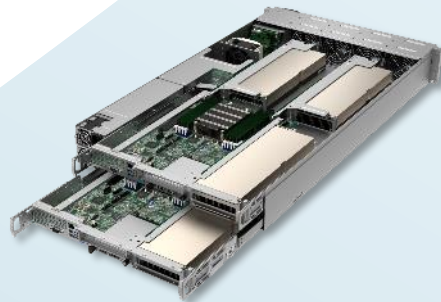
Delta:

- 424GO-NART



2U 2-node:

- 2114GT-DNR



Redstone:

- 2124GQ-NART



GPU Optimized 4U Server: AS –4124GS-TNR



DP 4U GPU optimized server designed with 160 direct attached PCI-E Gen 4 Lanes



Key Features

- Dual AMD EPYC™ 7002/7003 Series Processors
- 32 DIMMs up to 8TB DDR4 3200MHz
- 160 Direct attached PCIe lanes, Flexible Architecture
- PCIe Gen 4.0

Key Applications

- AI / ML / DL
- Cloud gaming
- Molecular Dynamic Simulation
- HPC



Specifications

CPU – Dual Socket

Dual AMD EPYC™ 7002/7003 Series Processors
Up to 128 Cores, CPU TDP up to 280W

Memory – 32 DIMM Slots

32 DIMMs, up to 8TB Registered ECC DDR4
3200MHz SDRAM

Drives – 2 SATA Drive Bays

2x 2.5" SATA in Raid 1 via onboard Marvell
4x NVMe*

Expansion – Flexible PCI-E Slots

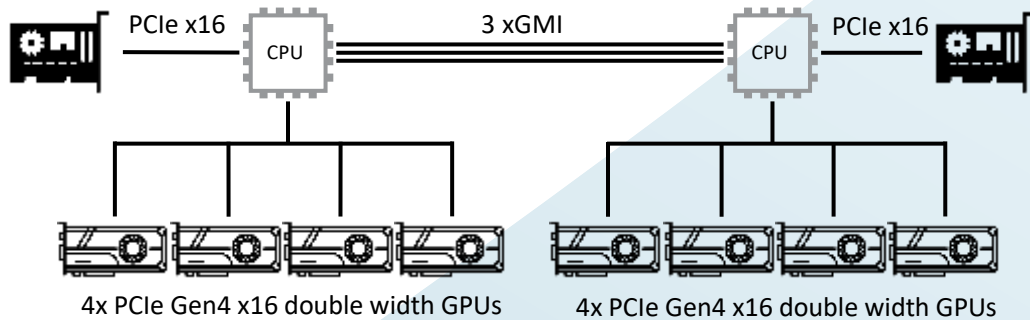
9x PCI-E 4.0 x16 or optional 10x PCI-E 4.0 x16*

Networking – Dual 1GbE

2x RJ45 10GbE, 1x RJ45 1GbE IPMI
Optional AIOM (flexible Networking)

Power Supply – 2+2 Redundant

4x 2000W Titanium Level



Subject to change without notice

* Limitation on Storage based on Expansion slots

GPU Optimized 2U : AS –2114GT-DNR

UP Multi-node 8DIMM 2U 2-node, supports 3 double width GPUs



Front View



Rear View



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz per node
 - 3 double width GPUs
 - AIOM
 - PCIe Gen 4.0
- **Key Applications**
 - Media/Video Streaming
 - AI Inference and Machine Learning
 - Cloud Gaming

Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 2 NVMe Drive Bays 2x NVMe 2x M.2 NVMe	Expansion – Flexible PCI-E Slots 4x PCI-E 4.0 x16
Networking – Flexible Networking AIOM x8	Power Supply – 2+2 Redundant 2x 2600W Titanium Level per chassis

Subject to change without notice

HGX A100 4-GPU (Redstone) Server: AS -2124GQ-NART



2U NVIDIA SXM A100 + 4-GPU AMD EPYC CPU System



- **Key Features**

- Supports 4 A100 40GB SXM4 GPUs
- Direct connect PCI-E Gen 4 Platform with NVIDIA® NVLink™
- Dual AMD EPYC™ 7002/7003 Series Processors

- **Key Applications**

- AI Compute/Model Training/Deep Learning
- High-performance Computing (HPC)



Specifications

CPU – Dual Socket Dual AMD EPYC™ 7002/7003 Series Processors Up to 128 Cores, CPU TDP up to 280W	Memory – 32 DIMM Slots 32 DIMMs, up to 8TB Registered ECC DDR4 3200MHz SDRAM
Drives – 4 Hot-Swap Bays 4x 2.5" SAS/SATA/NVMe Hybrid	Expansion – 5 PCI-E Slots 4x PCI-E Gen 4 x16 LP 1x PCI-E Gen 4 x8 LP
Networking – Dual 10GbE 2x RJ45 10GbE 1x RJ45 1GbE IPMI	Power Supply – 1+1 Redundant 2x 2200W Titanium Level 2x 3000W Titanium Level (Coming Soon)

Subject to change without notice

HGX A100 8-GPU (Delta) Server: AS -4124GO-NART



4U NVIDIA SXM A100 + 8-GPU AMD EPYC CPU System



- **Key Features**

- Supports 8 A100 40GB SXM4 GPUs
- 8 NIC for GPU direct RDMA (1:1 GPU ratio)
- Direct connect PCI-E Gen 4 Platform with NVIDIA® NVLink™
- Dual AMD EPYC™ 7002/7003 Series Processors
- 4 NVMe for GPU Direct Storage & Flexible I/O with AIOM

- **Key Applications**

- AI Compute/Model Training/Deep Learning
- High-performance Computing (HPC)



Specifications

<p>CPU – Dual Socket Dual AMD EPYC™ 7002/7003 Series Processors Up to 128 Cores, CPU TDP up to 280W</p>	<p>Memory – 32 DIMM Slots 32 DIMMs, up to 8TB Registered ECC DDR4 3200MHz SDRAM</p>
<p>Drives – 10 Drive Bays 10x 2.5" NVMe (8 from PCIe switch & 2 from CPU) 2x M.2 NVMe</p>	<p>Expansion – 10 PCI-E Slots 8x PCI-E x16 from PCI-E switch 1x PCI-E x16 and 1x PCI-E x8 from CPU</p>
<p>Networking – Flexible network via AIOM AIOM 1x RJ45 1GbE IPMI</p>	<p>Power Supply – 2+2 Redundant 4x 2200W Platinum Level or 4x 3000W Titanium Level</p>

Subject to change without notice

Towers



4U Towers

ATX board and Threadripper Pro

Mini Tower:

- 3014TS-i



Threadripper:

- 5014A-TT

Mini Tower: AS –3014TS-i

UP Mini Tower 8DIMM, based on ATX board



- **Key Features**
 - Single AMD EPYC™ 7002/7003 Series Processors
 - 8 DIMMs up to 2TB DDR4 3200MHz
 - 4 internal 3.5" SATA + 4 internal 2.5" SATA
 - PCIe Gen 4.0
- **Key Applications**
 - CAD and 3D modeling
 - Simulation and Creation Design
 - Data Sharing/storage
 - Centralized backup

Specifications

CPU – Single Socket Single AMD EPYC™ 7002/7003 Series Processors Up to 64 Cores, CPU TDP up to 280W	Memory – 8 DIMM Slots 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 4 3.5" + 4 2.5" Drive Bays 4 internal 3.5" SATA 4 internal 2.5" SATA 2 M.2	Expansion – 3 PCI-E Slots 5x PCI-E Gen 4 x16 2x PCI-E Gen 4 x8
Networking – Dual 1GbE 2x RJ45 1GbE	Power Supply 900W

Subject to change without notice

Full Tower 6U: AS –5014A-TT

Ryzen Threadripper Pro 3000WX series, Full tower



- **Key Features**

- Ryzen™ Threadripper™ PRO 3000WX Series Processors
- 8 DIMMs up to 2TB DDR4 3200MHz
- PCIe Gen 4.0

- **Key Applications**

- Media and Entertainment Content Creation
- Product Design and Engineering Simulation
- AI and Deep Learning



Specifications

CPU – Single Socket Single AMD Ryzen™ Threadripper™ PRO 3000WX Series Processors – Up to 64 Cores	Memory – 8 DIMM Slots 8 DIMMs, up to 2TB Registered ECC DDR4 3200MHz SDRAM
Drives – 4 + 2 Drive Bays 4 fixed internal 3.5"/2.5" SATA 2 fixed front 2.5" SATA 4 M.2	Expansion – 6 PCI-E Slots 6x PCI-E Gen 4 x16
Networking – Dual 1GbE 1x RJ45 10GbE	Power Supply 2000W Platinum Level Power Supply

Subject to change without notice

EPYC Milan Processors



Model Number	SMC P/N	TDP (W)	cTDP range (W)	Cores / Thread	Base Freq (GHz)	Max Boost Freq (GHz)	L3 \$ (MB)	DDR Channels	PCIe	Max DDr Freq (1DPC)
7763	PSE-MLN7763-0312	280	225 – 280	64/128	2.45	3.5	256	8	128	3200
7713/P*	PSE-MLN7713-0344 PSE-MLN7713P-0337	225	225 – 240	64/128	2.0	3.675	256	8	128	3200
7663	PSE-MLN7663-0318	240	225 – 240	56/112	2.0	3.5	256	8	128	3200
7643	PSE-MLN7643-0326	225	225 – 240	48/96	2.3	3.6	256	8	128	3200
7543/P*	PSE-MLN7543-0345 PSE-MLN7543P-0341	225	225 – 240	32/64	2.8	3.7	256	8	128	3200
7513	PSE-MLN7513-0334	200	165 – 200	32/64	2.6	3.65	128	8	128	3200
7453	PSE-MLN7453-0319	225	225 – 240	28/56	2.75	3.45	64	8	128	3200
7443/P*	PSE-MLN7443-0340 PSE-MLN7443P-0342	200	165 – 200	24/48	2.85	4.0	128	8	128	3200
7413	PSE-MLN7413-0323	180	165 – 200	24/48	2.65	3.6	128	8	128	3200
7343	PSE-MLN7343-0338	190	165 – 200	16/32	3.2	3.9	128	8	128	3200
7313/P*	PSE-MLN7313-0329 PSE-MLN7313P-0339	155	155 – 180	16/32	3.0	3.7	128	8	128	3200
75F3	PSE-MLN75F3-0313	280	225 – 280	32/64	2.95	4.0	256	8	128	3200
74F3	PSE-MLN74F3-0317	240	225 – 240	24/48	3.2	4.0	256	8	128	3200
73F3	PSE-MLN73F3-0321	240	225 – 240	16/32	3.5	4.0	256	8	128	3200
72F3	PSE-MLN72F3-0327	180	165 – 200	8/16	3.7	4.1	256	8	128	3200

*P = UP only

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